

ABSTRACT OF THE DISCLOSURE

According to one aspect of the present invention, an electronic assembly and a method of forming an electronic assembly are provided. A semiconductor package includes a package substrate with a microelectronic die mounted to a first side and contact formations attached to a second side thereof. A stress compensation layer is formed on the first surface between the contact formations. The semiconductor package is then attached to a circuit board leaving an air space between the stress compensation layer and the circuit board. The stress compensation layer reduces stress on the contact formations and increases solder joint reliability.